

产品名称 Description		

	产品料号 Part No.	产品型号规格 Description
包括但不限于右边所列产品	3720MXXX022XXXXXX	0.5BTB-NPin 公座H2.2
	3720MXXX012XXXXXX	P型0.5BTB-NPin 公座H1.23
	3720MXXX037XXXXXX	0.5BTB-NPin 公座H3.7
	3723-MXXX008XXXXXX	0.5BTB-NPin 双槽型 公座H3.7
	3723-MXXX010XXXXXX	0.5BTB-NPin 双槽型 公座H1.0
	3723-MXXX013XXXXXX	0.5BTB-NPin 双槽型 公座H1.3
	3723-MXXX020XXXXXX	0.5BTB-NPin 双槽型 公座H2.0
	3720FXXX013XXXXXX	0.5BTB-NPin 母座H1.32
	3720FXXX023XXXXXX	0.5BTB-NPin 母座H2.3
	3720FXXX043XXXXXX	0.5BTB-NPin 母座H4.3
	3720FXXX018XXXXXX	P型0.5BTB-NPin 母座H1.85
	3723-FXXX022XXXXXX	0.5BTB-NPin 双槽型 母座H2.2
	3723-FXXX030XXXXXX	0.5BTB-NPin 双槽型 母座H3.0
	3723-FXXX035XXXXXX	0.5BTB-NPin 双槽型 母座H3.5
	3723-FXXX040XXXXXX	0.5BTB-NPin 双槽型 母座H4.0
	3723-FXXX045XXXXXX	0.5BTB-NPin 双槽型 母座H4.5

1. SCOPE ()

This product specification defines the product performance and the test methods to ascertain the performance of the (0.5mm Board To Board) Connector ,which si designed and manufactured by JILN Electronic Co.,Ltd.This product specification is applicable but not only for those part numbers which be shown in the cover page.

本产品规格书规定了由锦凌电子有限公司设计生产的(0.5mm板对板)型连接器,产品的特性及产品的测试方法。本产品规格书适用于但不局限于封面所显示的产品料号

2. REFERENCE DOCUMENTS

MIL-STD-1344	Test method for electrical connector 电子连接器方法
MIL-STD-202	Test method for electrical connectors 电子零件测试方法
EIA364	Test method for electrical connectors 电子零件测试方法
JIS C 0051	Test method for electrical connectors 电子零件测试方法
MIL-G-45204C	Specification for gold plating 镀金规格
IEC-512-3	IEC standard for current carrying capacity tests IEC 电流测试标准
QQ-N-290A	Specification for nickel plating 镀镍规格
MIL-P-81728A	Specification for tin/lead plating 镀锡规格
MIL-T-10727B	Specification for tin plating 镀锡规格
UL498	UL standard for safety of attachment plug and receptacle UL安规要求标准
IEC62321	Determination of total lead &cadmium content 总铅和总镉含量测定
IEC62321	Determination of total lead &cadmium content 总铅和总镉含量测定
IEC62321	Determination of heavy metals content 重金属含量测定
IEC62321	Determination of total lead &cadmium content 总铅和总镉含量测定

3. FEATURE & DIMENSIONS

3.1. PRODUCT DIMENSION (产品尺寸)

These connectors shall have the dimensions as shown in drawing.

本产品的相关尺寸参见图面.

3.2. PCB/panel layout (! 电" 板# 局)

The recommended PCB layout is shown in drawing.

本产品适用的 PCB layout 参见图面.

3.3. BILL OF MATERIAL (\$料%&)

Harmful material controlling follows the requirements of RoHS. The bill of material is described in drawing.

有害 () * + , - RoHS. / 要求。本产品○用的\$料参见图面。

3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC (1 2及电器特性)

The connector shall have the mechanical and electrical performance as described in drawing. 本产品的1 2及电器特性参见3方4 5 6 (测试要求7 方法) .

3.5. PACKAGING (包8)

Products shall be packaged according to requirements specified in purchase order for safe delivery,connector container and the packaging method are shown in package specification. 产品9: ; < = . 定要求包8 , 包8 \$料7 包8方> 参见产品包8规? .

3.6. RATING CURRENT AND RATING VOLTAGE (@定电流7 @定电A)

Rating current is (0.5)A , rating voltage is (50)V DC/AC RMS.

@定电流: (0.5) A , @定电A (50) V DC/AC RMS.

3.7. STORAGE AND OPERATING TEMPERATURE (BC 7 0用DE)

Temperature range:-(40)F G+(105)F , including terminal temperature rise for rating current. DE ? H : -(40)F G+(105)F , 包含接I J 子的@定电流DK

4. Environmental ()

4.1.SOLDERABILITY (9L 性)

Connectors meet solder-ability to MIL-STD-202,and shall be free of contaminants.

(产品9L 性, - MIL-STD-202标准规定的相关要求, 5面不M有NO(.)

4.2.INFRARED REFLOW (PQRS 流L)

Each cycle consists of three consecutive

(T U L 接V W 包括X U 连Y Z [, 见4 5 X)

1. Preheat \]

Increase in temperature not to exceed 3^C per second.

(DE _ ` a 不bc 3^C /d)

2. Soldering (L 接)

Maximum allowable time above reflow temperature of 150^C is 370 seconds. Maximum temperature in this interval is 260^C, duration is 20~40 seconds.

(S流L DE e 150^Cf g的hi j k bc 370d。j l DE 260^Chi 20~40d。)

3. Cool Down (mn)

Cool down shall not exceed 6°C per second.

(mn a E 不bc 6°C/d.)

4.3. RESISTANCE TO SOLDER HEAT (o L 接])

WAVE SOLDER (p q L 接)

Each cycle consists of three consecutive phases.

(T U L 接VW包括X U连Y Z [.)

1.Preheat (\])

The steady temperature of the preheat zone is 90G125F .

\] r j s DE * + e 90G125F .

2. Soldering (L 接)

To avoid the secondary tin-melting, the temperature on PCB upper surface is 160°C Max. for products with lead, or 200°C Max. for lead-free products. The temperature of the PCB bottom surface shall not be exceed 100°C more than the temperature of the PCB upper surface. The peak temperature is during 230~250°C for products with lead, or 255~265°C for lead-free products. The tin dip time is duration for 3~5 seconds.

(有铅产品板面DE 不Mbc 160F , t 铅产品板面DE 不的bc 200F , f u v w x 零件y z { 锡。板面DE 7板| 的DE D} 不Mbc 100F。板3DE q ~有铅产品 ! e 230G250F , t 铅产品* + e 260G270F ." 锡hi * + e 3G10d.)

3.Cool Down (mn)

Cool down shall not exceed 6F per second.

(mn a E 不bc T d 6F)

Note:

Device temperature measurements are referenced from the top-center of the package outer surface.

(设# DE 量测hf \$%&' i () 测量* 准.)

PERFORMANCE AND TEST DESCRIPTION ()

REQUIREMENT (要求)

Product is designed to meet electrical,mechanical,and environmental performance requirements specified in Table 1

(本产品设计, - 456所列的1 2 , 电器及+, 要求)

TEST CONDITION (测试- 件)

Unless otherwise specified,all tests shall be performed at ambient environmental conditions.

(. / 特012, 所有测试的3D- 件345)

SAMPLE SELECTION (6品78)

Test samples shall be selected at random from current production. No test samples shall be reused.

Samples are pre-conditioned with 10cycles of durability. Each group shall be containing 5 test samples.

(测试6品\$9生产的产品' : 1; <, 所有测试c的6品不M重=O用。6品f \ > ? @10z , T A测试BC有5U6品.)

5.4. TEST SEQUENCE (测试DE)

Product qualification test sequence as shown in Table II.

(产品品F 测试DE见45y)

Table I: Test Requirements and Test Methods

456 : 测试要求和测试方法

Items (GH)	Requirements (要求)	Test Methods (测试方法)
1. Confirmation of Product (产品I J)	Product shall be conforming to the requirements of applicable product drawing 产品KL, - 相关产品图面的要求	Visually dimensions and functionally inspected per applicable product drawing. : ; 产品相关图面, MN产品的QO 尺寸及PQ
2. Contact Resistance (接I RS)	30 mT Max.Inital UVWXj Y 30 mT	Subject mated contacts assembled in housing to closed circuit of 100 mA max.20 mV max. 所Z [定e Q\] 的J 子连接^ 6U封_ S" ' 测试: 电流100mA max,电A 20 mV max. 适用: MIL-STD-202, 方法 307。
3. Insulation Resistance (^ a SR)	500 MT Min j b 500 MT	Measure by applying test potential between the adjacent contacts,and between the contacts and ground in the mated connector . MIL-STD-202, Method 302, Condition B (500 V DCc10%). 测试产品相dJ 子i f 及J 子7接ei 的电S 适用: MIL-STD-202,方法 302, f 件 B (500V DCc10%)
4. Dielectric Withstanding Strength (o电A)	Connector must withstand test potential os ,annec	

<p>5. Durability (Repeated Mating/Un-mating) 耐久性</p>	<p>Contact Resistance: 50 mT Max. after testing. 测试接触电阻 SRj Y 50mT</p>	<p>Repeat mate and unmated for connector 500 cycles, At a speed of 300 mm/minute 重复插拔 500 次, 速度为 300mm/分钟</p>
<p>6. Connector Pin Mating/Un-mating Force 插拔力</p>	<p>Mating force: (60)gf/Pin Max. Un-mating force: (10)gf/Pin Min. 插力 ≤ (60) gf/Pin 拔力 ≥ (10) gf/Pin</p>	<p>At a speed of 25c3 mm/minute, apply axial insert the mating part into fully or pull out from the subject product. 速度为 25c3mm/分钟, 施加轴向力将配合件完全插入或从被测产品上拔出</p>
<p>7. Contact Retention Force 接触保持力</p>	<p>(0.20)kgf/Pin Min. ≥ (0.20)kgf/Pin</p>	<p>Apply axial pull out force at a 25c3mm/minute On the contact assembled in the housing. 速度为 25c3mm/分钟, 施加轴向拉力于安装在壳体上的接触点</p>
<p>8. Thermal shock 热冲击</p>	<p>After testing, no damage, Contact Resistance 35 mT max.. Dielectric Strength should be OK, Insulation Resistance should be 500 MT min. (测试后, 产品无损伤, 接触电阻: 35 mTj Y # o 电测试 OK, %SR 500MTj b;)</p>	<p>is no more than 30 seconds. Total 5 cycles. MIL-STD-202, Method 107D, condition A. (DE & ' ? H : -55°C ~ +85°C # \$ -55°C (V , 30 i j m) ^ +85°C # *) hi 不 bc 30 d # + 10U , + . - 用 : MIL-STD-202 , 方法 107 , - 件 A.)</p>
<p>9. Humidity 湿度</p>	<p>After testing, no damage, Contact Resistance 35mT max.. Dielectric Strength should be OK, Insulation Resistance should be 500MTmin. 测试后, 产品无损伤, 接触电阻: 35 mTj Y # o 电测试 OK, %SR 500MTj b;</p>	<p>Temperature: 40c2°C. Relative Humidity: 90-95%. Duration: 96 Hours. MIL-STD-202, Method 103, condition B. DE : 40c2°C. 相对湿度: 90-95%。 ! Y hi : 96 b O。 适用 : MIL-STD-202 , 方法 103 , - 件 B。</p>
<p>10. Solder ability (9L 性)</p>	<p>giving a magnification of 10 X for any damage such as pinholes, void or rough surface. 6 品 e 测试 45m , e 1 Y 23 * 10 2 的显 453 , MNQO! " 6 : b 7 , 8L , QO9: E #)</p>	<p>Soldering time: 4 to 6 seconds. Temperature: 260c5°C. MIL-STD-202, Method 208. L 接 hi : 4~6 d。 DE : 260c5°C。 L 锡面: : 95%f g 适用 : MIL-STD-202 , 方法 208。</p>

<p>11. Humidity (. D. /)</p>	<p>After testing, no damage, Contact Resistance 35mT max.. Dielectric Strength should be OK, Insulation Resistance should be 500MT min. 测试m,产品t ! " ,接I SR : 35 mTj Y# o电A测试 OK, \$%SR 500MTj b;</p>	<p>Temperature: 40c2^C. Relative Humidity: 90-95%. Duration: 96 Hours. MIL-STD-202, Method 103, condition B. DE : 40c2^C. 相对/ E : 90-95%. ! Yhi : 96 b O。 适用 : MIL-STD-202 , 方法 103 , - 件 B。</p>
<p>12. Solder ability (9L 性)</p>	<p>giving a magnification of 10 X for any damage such as pinholes, void or rough surface. 6品e 测试45m , e 1 Y 2 3 * 10 2的显453 , MNQO! " 6 : b 7 , 8L , QO9: E #)</p>	<p>Soldering time: 4 to 6 seconds. Temperature: 260c5^C. MIL-STD-202, Method 208. L接hi : 4~6 d。 DE : 260c5^C. L锡面: : 95%f g 适用 : MIL-STD-202 , 方法 208。</p>

Table II: Product Qualification Test Sequence

45y : 产品测试DE

Test Description 测试 < Z	TestGroup 测试i A						
	A	B	C	D	E	F	G
1. Conformation of Product 产品I J	1,7	1,4	1,9	1,9	1,3	1,9	1,9
2. Contact Resistance 接I SR	2,6		2,6	2,6		2,6	2,6
3. Insulation Resistance ` a SR	3		3,7	3,7		3,7	3,7
4. Dielectric Withstanding Voltage o电A	4		4,8	4,8		4,8	4,8
5. Durability (Repeated Mating/Un-mating) oI 性	5						
6. Connector Pin Mating/Un-mating Force &=J 子? p/@r		2					
7. Contact Retention Force J 子x !		3					
8. Thermal Shock] ~			5				
9. Humidity (Steady State) . D. /				5			
10. Solder-ability 9L 性					2		
11. Salt Spray > ?						5	
12. High Temperature Life I D '							5

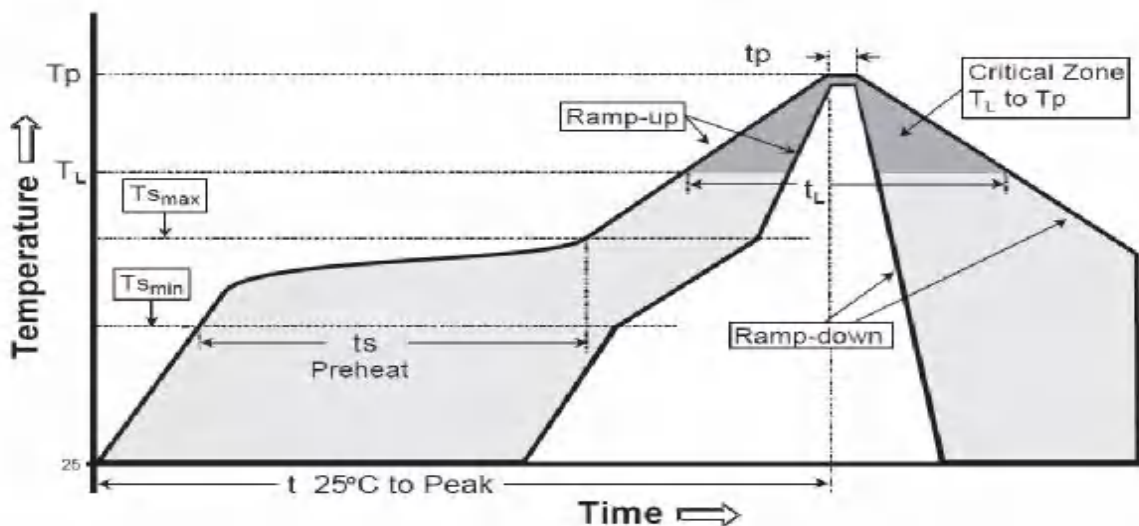
Table III: Reflow Soldering Profile

附表三：回流焊接曲线图

Lead-free reflow profile requirements:

t 铅S流L接@R :

Parameter 参3	Reference 参A	Specification 规格
K Dr Ramp-up	25°C ~ 150°C	3°C /S Max
\] r (Pre-heating) Temperature Min(Tsmin) Temperature Max(Tsmax) Time(Tsmin to tsmax)	150F ~ 200F	60~180sec
Time maintained above(x ! h i) Temperature(TL) Time(tL)	217°C	60~150sec
Time within 5°C of actual peak Temperature(tp)	260-/+5°C	20~40sec
mnr Cooling	Ramp-Down Rate	6°C /S(Max)
Time 25°C to Peak Temperature	25°C ~ Peak Temp.	8 minutes maximum



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile largely dependent on the reflow equipment.

BU@R图CDEF件器件L接R]的G本要求。H用e对L接'的] I J方>C] K对流。L ^特定@R图e MNDE O要: P 7 S流L接设#。

5.

5.1 (料的包8对(料有6定的x QR用和S封R用 , x T (料e UVc W' 不Xh ^! " 。

5.2 包8YHZ [u\ , u] ^ uA和u_` 要求。

5.3 j b包8&F 的标a KL有bcd标^产品型号^名称^ (料ef 和3量。

5.4 包85Y的产品 , He + , DE * -10F G+40F , 相对/ Ee 80%f 3 , VH8K' t g性 ,
h性wi j k l 性K} 的mn] oB , egZ - 件3 , p生产qWQr s t oBW , eB s t u
(料v * - 格品。